Tool ID: 411
Tool Location: 121

Equipment Information Sheet

Class 1 Photolithography Hot Plates

Manager: Giovanni Sartorello 607-254-4853
Backup: Garry Bordonaro 607-254-4936

Calls to staff phones will be automatically forwarded to their cell phones during accessible hours. At other times leave a message or send them an email.

SAFETY

- Surfaces can be hot.

USAGE RESTRICTIONS

- General photolithography training (online and in-person) is required to use this tool.

SCHEDULING/SIGN-UP RESTRICTIONS

Minimum Tool Time: 0 minutes

- A group may have no more than 2 hotplates in simultaneous operation.

MATERIALS COMPATIBILITY CATEGORY

Tool Category 5: Class A and B Metals and Compounds

Allowed	Not Allowed
Tool category 1/1E, 2, 3, and 4 materials	
Silicon Based Substrates and Films	
III/V compound Semiconductors	
Glass Substrates	
PECVD and ALD Films	
Cured organics and baked Photoresist	
CNF Class A, B, and Refractory metals	
Exposed Gold, Silver, Copper	
Alkali and Alkaline Compounds	
Organic/Biology Molecules prepared-w/salt buffers	
High Vapor Pressure Materials (Mg, Ca, Zn)*	* Some tool restrictions on high vapor pressure materials may apply
Soft organic materials	

High Vapor Pressure Metals and Compounds are materials that have a vapor pressure above 1e-6 Torr at 400 C.

Additional Material Restrictions and Exceptions

- Class 1 materials **only** (most positive resist, nLOF, i-line and DUV materials, P-20 primer).
- The backside of all substrates must be inspected and cleaned prior to baking.
- No low temperature materials.

Last Updated: 03/21/2025